

# PROBE TIP SELECTION GUIDE



PROBING	MODEL	TIP RADIUS	MATERIAL	SHANK	DIAMETER	LENGTH	COMMENTS
Small Geometry	DC-11014	0.10 µm	Tungsten	Nickel	20 mil	35 mm (1.25")	Submicron probe for small feature probing - can easily be bent or cut to length
Small Geometry	DC-11018	0.15 µm	Tungsten	Nickel	20 mil	35 mm (1.25")	
Small Geometry	DC-11015	0.25 µm	Tungsten	Nickel	20 mil	35 mm (1.25")	
Small Geometry	DC-11003	0.35 µm	Tungsten	Nickel	20 mil	35 mm (1.25")	
Small Geometry	DC-11012	0.50 µm	Tungsten	Nickel	20 mil	35 mm (1.25")	
Small Geometry	DC-11045	1.0 µm	Tungsten	Nickel	20 mil	35 mm (1.25")	
<b>TUNGSTEN</b>							<b>GENERAL PURPOSE PROBING</b>
Small Geometry	DC-11010	0.60 µm	Tungsten	Tungsten	20 mil	35 mm (1.25")	Submicron solid tungsten probe for small feature probing
Small Geometry	DC-11029	0.75 µm	Tungsten	Tungsten	20 mil	35 mm (1.25")	
Small Geometry	DC-11004	1.0 µm	Tungsten	Tungsten	20 mil	35 mm (1.25")	Structures >4.0 µm
Small Geometry	DC-11030	1.2 µm	Tungsten	Tungsten	20 mil	35 mm (1.25")	Structures >5.0 µm
Small Geometry	DC-11002	2.0 µm	Tungsten	Tungsten	20 mil	35 mm (1.25")	Structures >8.0 µm
Bond Pads	DC-11005	5.0 µm	Tungsten	Tungsten	20 mil	35 mm (1.25")	Structures >20.0 µm
Bond Pads	DC-11006	7.0 µm	Tungsten	Tungsten	20 mil	35 mm (1.25")	Structures >30.0 µm
Bond Pads	DC-11008	10.0 µm	Tungsten	Tungsten	20 mil	35 mm (1.25")	Structures >40.0 µm
Bond Pads	DC-11009	12.5 µm	Tungsten	Tungsten	20 mil	35 mm (1.25")	Structures >50.0 µm
Bond Pads	DC-11013	20.0 µm	Tungsten	Tungsten	20 mil	35 mm (1.25")	Structures >80.0 µm
Bond Pads	DC-11007	25.0 µm	Tungsten	Tungsten	20 mil	35 mm (1.25")	Structures >100.0 µm
Bond Pads	DC-11002-30	3.5 µm	Tungsten	Tungsten	20 mil	35 mm (1.25")	
Bond Pads	DC-11040	50.0 µm	Tungsten	Tungsten	20 mil	35 mm (1.25")	
<b>GOLD PLATED</b>							<b>PROBE GOLD CONTACTS AND PADS – REDUCED CONTACT RESISTANCE</b>
Bond Pads	DC-11044	5.0 µm	Gold Plated	Tungsten	20 mil	35 mm (1.25")	
Bond Pads	DC-11038	7.0 µm	Gold Plated	Tungsten	20 mil	35 mm (1.25")	Features > 30.0µm
Bond Pads	DC-11031	10.0 µm	Gold Plated	Tungsten	20 mil	35 mm (1.25")	Features > 40.0 µm
Bond Pads	DC-11032	12.5 µm	Gold Plated	Tungsten	20 mil	35 mm (1.25")	Features > 50.0 µm
Bond Pads	DC-11033	15.0 µm	Gold Plated	Tungsten	20 mil	35 mm (1.25")	Features > 60.0 µm
Bond Pads	DC-11019	20.0 µm	Gold Plated	Tungsten	20 mil	35 mm (1.25")	Features > 80.0 µm
Bond Pads	DC-11034	25.0 µm	Gold Plated	Tungsten	20 mil	35 mm (1.25")	Features > 100.0 µm
Bond Pads	DC-11027	50.0 µm	Gold Plated	Tungsten	20 mil	35 mm (1.25")	
<b>TUNGSTEN CARBIDE</b>							<b>CUTTING AND HIGH TEMPERATURE OPERATIONS</b>
Bond Pads	DC-11022	5.0 µm	Tungsten Carbide	Tungsten Carbide	20 mil	35 mm (1.25")	Features > 20.0µm
Bond Pads	DC-11020	7.5 µm	Tungsten Carbide	Tungsten Carbide	20 mil	35 mm (1.25")	Features > 30.0µm
Bond Pads	DC-11036	10.0 µm	Tungsten Carbide	Tungsten Carbide	20 mil	35 mm (1.25")	Features > 40.0µm
Bond Pads	DC-11021	12.5 µm	Tungsten Carbide	Tungsten Carbide	20 mil	35 mm (1.25")	Features > 50.0µm
Bond Pads	DC-11035	20.0 µm	Tungsten Carbide	Tungsten Carbide	20 mil	35 mm (1.25")	Features > 80.0µm
Bond Pads	DC-11023	25.0 µm	Tungsten Carbide	Tungsten Carbide	20 mil	35 mm (1.25")	Features > 100.0µm
<b>BERYLLIUM COPPER</b>							<b>LOW CONTACT RESISTANCE – SOFT MATERIAL REDUCES PAD DAMAGE</b>
Bond Pads	DC-11028	5.0 µm	Beryllium Copper	Beryllium Copper	20 mil	35 mm (1.25")	
Bond Pads	DC-11001	7.0 µm	Beryllium Copper	Beryllium Copper	20 mil	35 mm (1.25")	
Bond Pads	DC-11024	10.0 µm	Beryllium Copper	Beryllium Copper	20 mil	35 mm (1.25")	
Bond Pads	DC-11025	12.5 µm	Beryllium Copper	Beryllium Copper	20 mil	35 mm (1.25")	
Bond Pads	DC-11026	20.0 µm	Beryllium Copper	Beryllium Copper	20 mil	35 mm (1.25")	
Bond Pads	DC-BE-11040	25.0 µm	Beryllium Copper	Beryllium Copper	20 mil	35 mm (1.25")	